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# PBSS5240X

40 V, 2 A PNP low V<sub>CEsat</sub> (BISS) transistor

19 October 2012

Product data sheet

## 1. Product profile

### 1.1 General description

PNP low V<sub>CEsat</sub> Breakthrough In Small Signal (BISS) transistor in a medium power and flat lead SOT89 Surface-Mounted Device (SMD) plastic package. NPN complement: PBSS4240X.

### 1.2 Features and benefits

- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability I<sub>C</sub> and I<sub>CM</sub>
- High efficiency due to less heat generation

### 1.3 Applications

- DC-to-DC conversion
- Supply line switching
- Battery charger
- LCD backlighting
- Driver in low supply voltage applications (e.g. lamps and LEDs)
- Inductive load driver (e.g. relays, buzzers and motors)

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-40	V
I <sub>C</sub>	collector current		-	-	-2	A
I <sub>CM</sub>	peak collector current		-	-	-3	A
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = -1 A; I <sub>B</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	310	mΩ
I <sub>CRM</sub>	repetitive peak collector current	t <sub>p</sub> ≤ 20 ms; δ ≤ 0.33; pulsed	-	-	-2.5	A



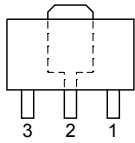
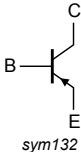
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## PBSS5240X

40 V, 2 A PNP low VCEsat (BISS) transistor

## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E	emitter	 <p style="text-align: center;">SOT89</p>	 <p style="text-align: center;">sym132</p>
2	C	collector		
3	B	base		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS5240X	SOT89	plastic surface-mounted package; die pad for good heat transfer; 3 leads	SOT89

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PBSS5240X	S48

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-40	V
$V_{CEO}$	collector-emitter voltage	open base	-	-40	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$I_C$	collector current		-	-2	A
$I_{CRM}$	repetitive peak collector current	$\delta \leq 0.33$ ; $t_p \leq 20$ ms; pulsed	-	-2.5	A
$I_{CM}$	peak collector current		-	-3	A
$I_B$	base current		-	-300	mA
$I_{BM}$	peak base current		-	-1	A
$P_{tot}$	total power dissipation	[1]	-	0.5	W
		[2]	-	0.95	W

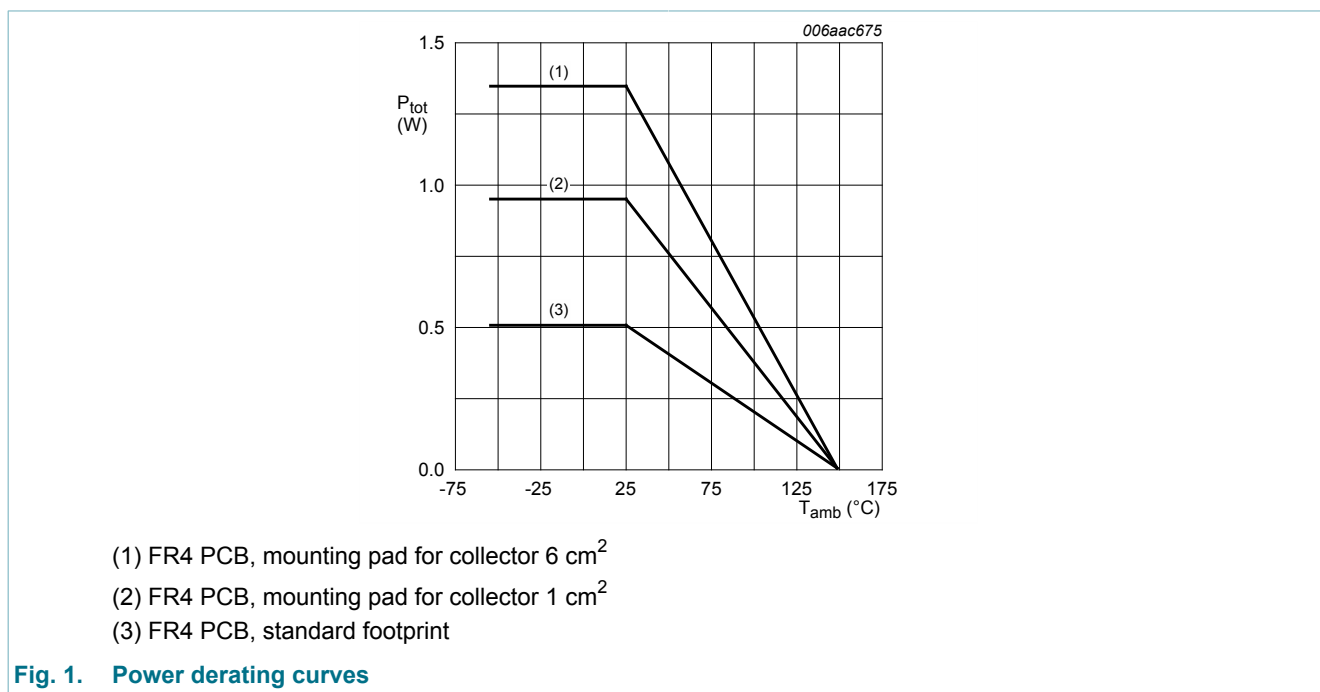
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40 V, 2 A PNP low VCEsat (BISS) transistor

Symbol	Parameter	Conditions		Min	Max	Unit
			[3]	-	1.35	W
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-65	150	°C
$T_{stg}$	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

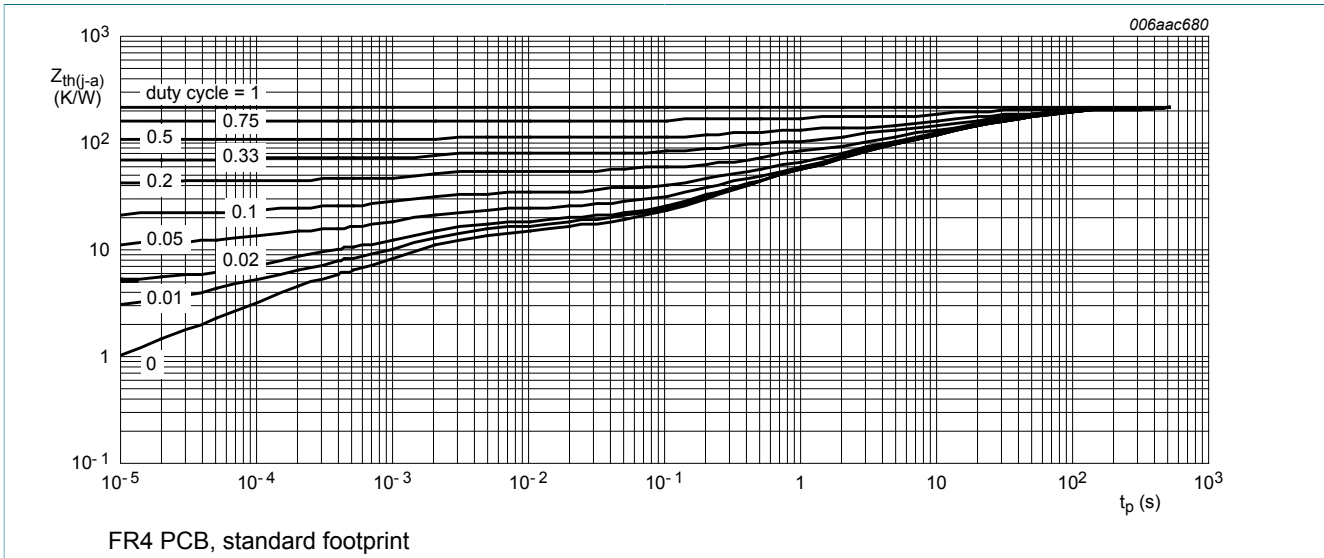


6. Thermal characteristics

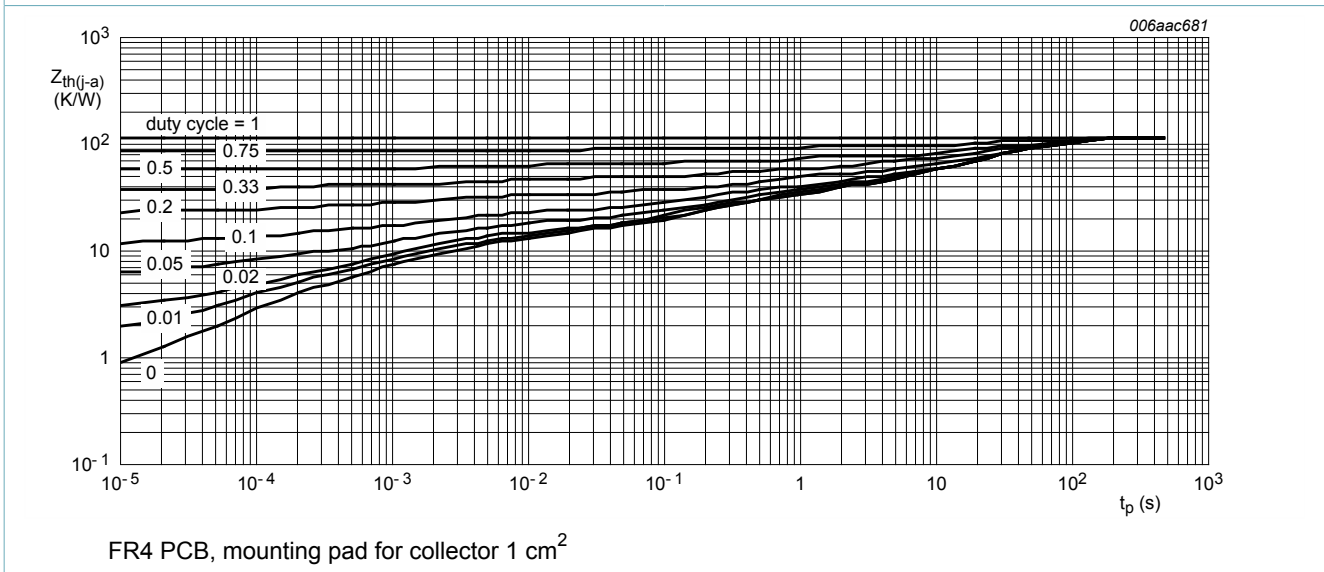
Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	250	K/W
			[2]	-	-	132	K/W
			[3]	-	-	93	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	16	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.



**Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

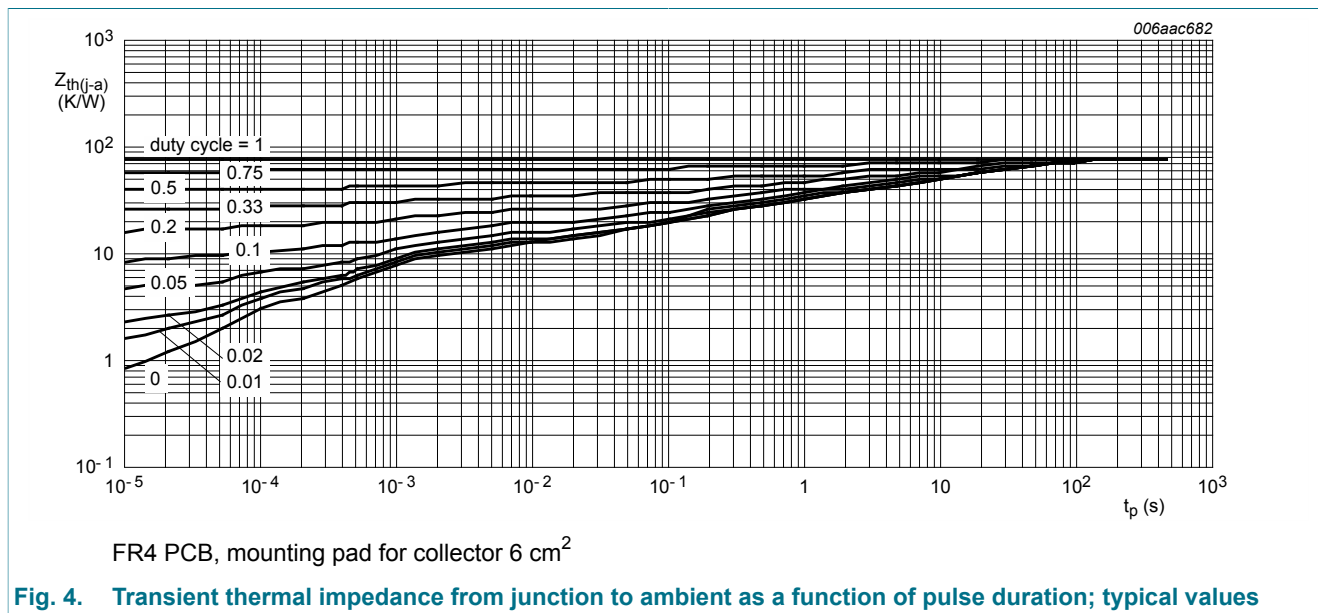


**Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

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**7. Characteristics**

**Table 7. Characteristics**

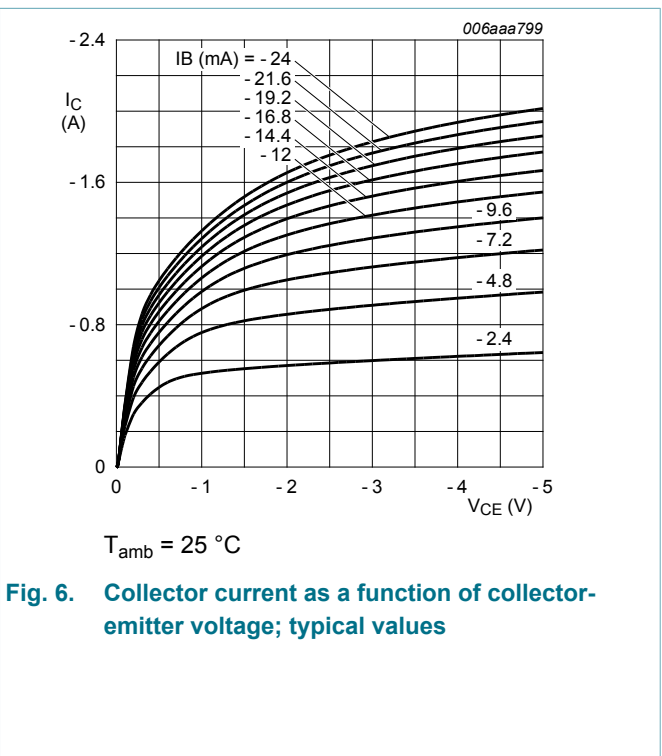
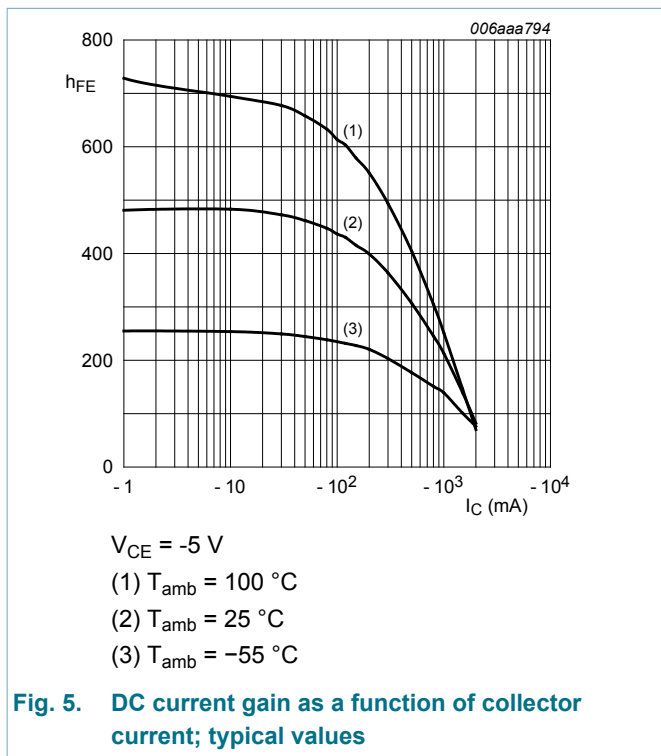
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -40 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
		V <sub>CB</sub> = -40 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	-50	µA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = -30 V; I <sub>B</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -1 mA; T <sub>amb</sub> = 25 °C	300	-	-	
		V <sub>CE</sub> = -5 V; I <sub>C</sub> = -500 mA; T <sub>amb</sub> = 25 °C	215	-	-	
		V <sub>CE</sub> = -5 V; I <sub>C</sub> = -1 A; T <sub>amb</sub> = 25 °C	145	-	-	
		V <sub>CE</sub> = -5 V; I <sub>C</sub> = -2 A; pulsed; t <sub>p</sub> ≤ 300 µs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	55	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -100 mA; I <sub>B</sub> = -5 mA; T <sub>amb</sub> = 25 °C	-	-	-140	mV
		I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-170	mV
		I <sub>C</sub> = -1 A; I <sub>B</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 µs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	-310	mV
		I <sub>C</sub> = -2 A; I <sub>B</sub> = -200 mA; pulsed; t <sub>p</sub> ≤ 300 µs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	-630	mV
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = -1 A; I <sub>B</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 µs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	310	mΩ

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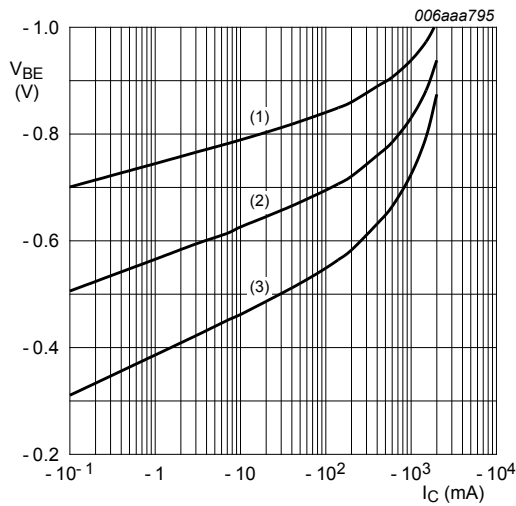
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -1\text{ A}$ ; $I_B = -100\text{ mA}$ ; pulsed; $t_p \leq 300\ \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-1.2	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -5\text{ V}$ ; $I_C = -1\text{ A}$ ; pulsed; $t_p \leq 300\ \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-1.1	V
$f_T$	transition frequency	$V_{CE} = -10\text{ V}$ ; $I_C = -50\text{ mA}$ ; $f = 100\text{ MHz}$ ; $T_{amb} = 25\text{ }^\circ\text{C}$	150	-	-	MHz
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}$ ; $I_E = 0\text{ A}$ ; $i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$ ; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	12	pF



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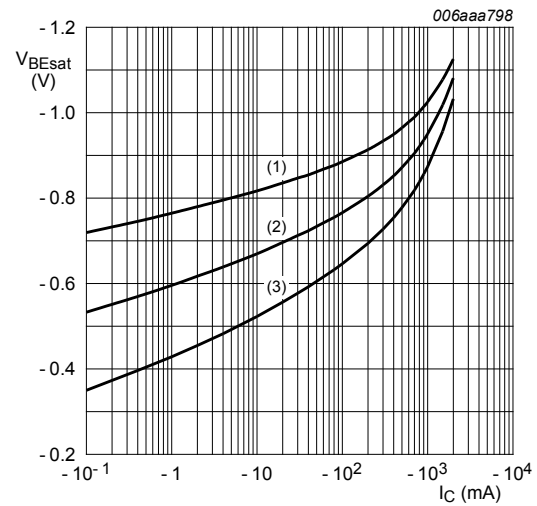
**PBSS5240X**

**40 V, 2 A PNP low VCEsat (BISS) transistor**



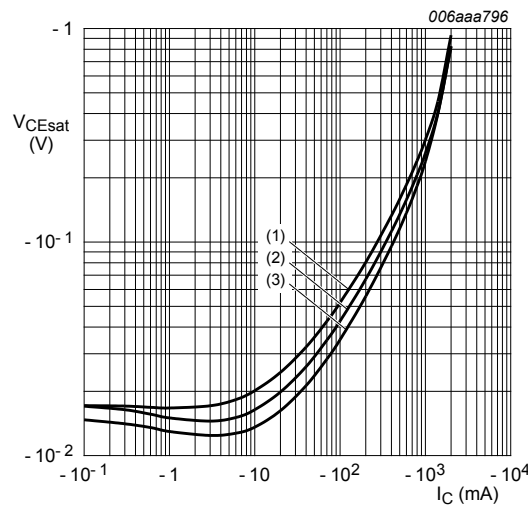
$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = -55\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

**Fig. 7. Base-emitter voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = -55\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 150\text{ }^\circ\text{C}$

**Fig. 8. Base-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -55\text{ }^\circ\text{C}$

**Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values**



## 8. Package outline

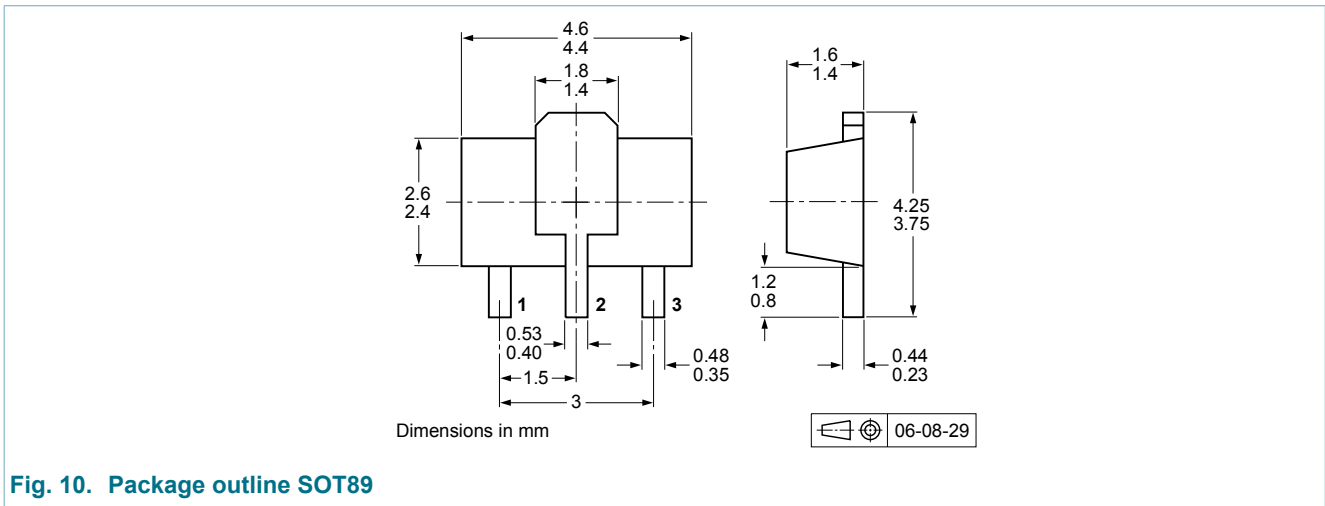


Fig. 10. Package outline SOT89

## 9. Soldering

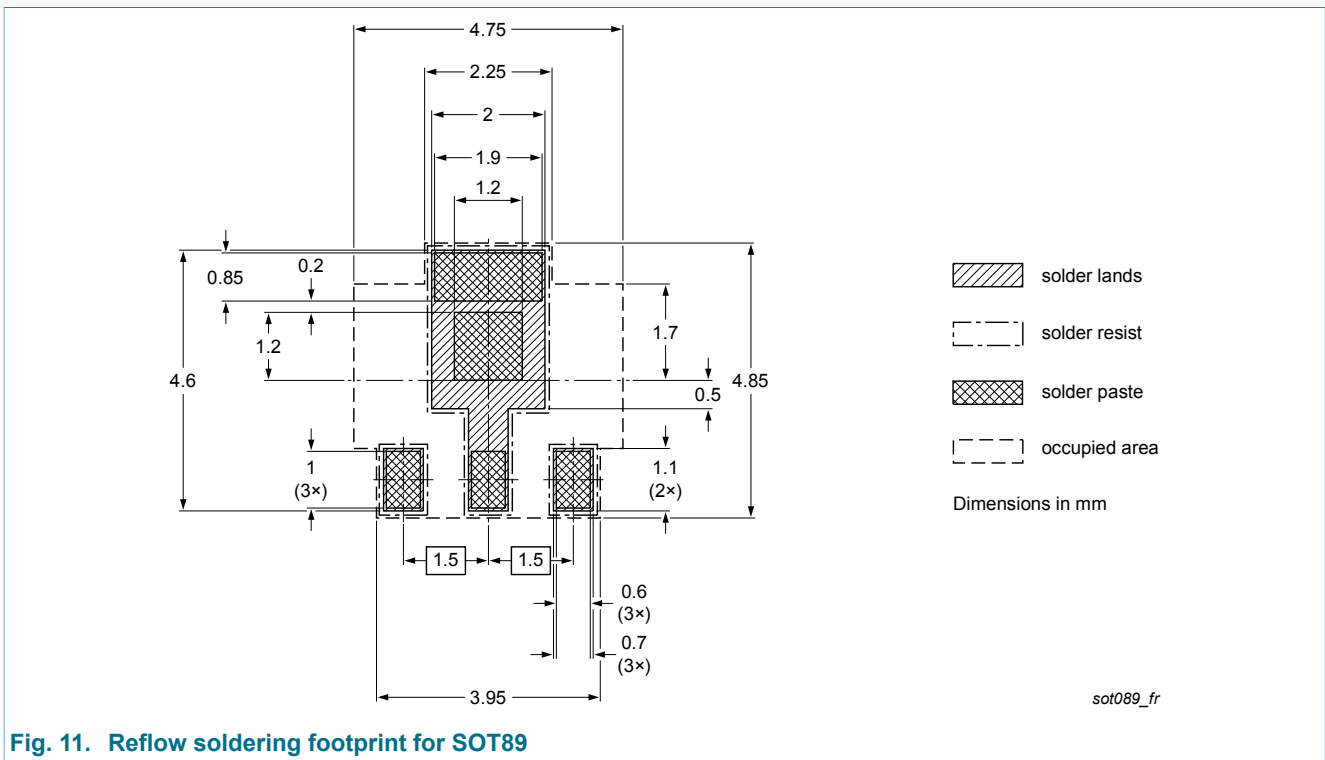
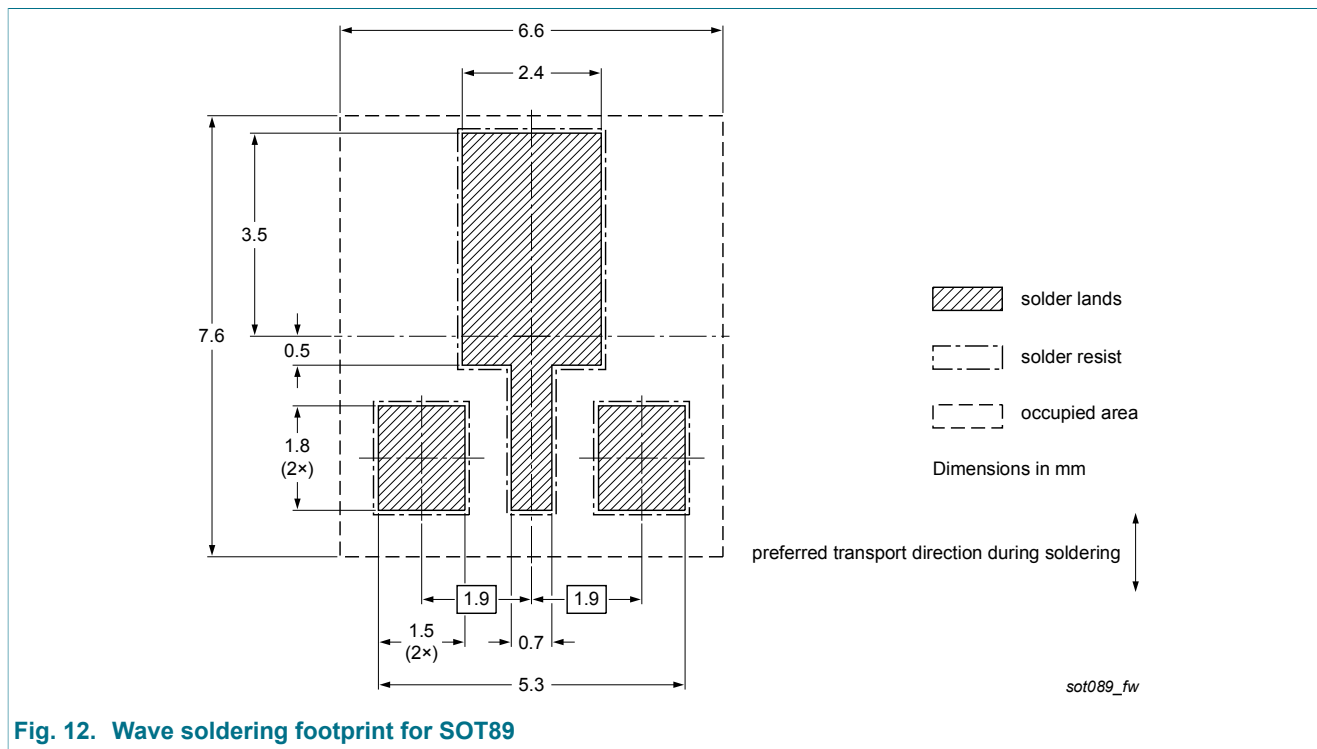


Fig. 11. Reflow soldering footprint for SOT89



## 10. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS5240X v.1	20121019	Product data sheet	-	-

## 11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 19 October 2012